

## Features

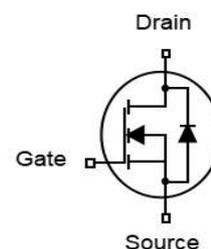
- N-Channel
- Excellent gate charge x  $R_{DS(on)}$  product(FOM)
- Very low on-resistance  $R_{DS(on)}$
- 150 °C operating temperature
- 100% EAS Tested

$V_{DS}$	60	V
$R_{DS(on),TYP@ V_{GS}=10V}$	1.1	mΩ
$R_{DS(on),TYP@ V_{GS}=4.5V}$	1.4	mΩ
$I_D$	240	A

DFN5x6



Part ID	Package Type	Marking	Packing
ZTG011N06GC	DFN5x6	ZTG011N06GC	5000pcs/Reel



## Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ , unless otherwise specified

Symbol	Parameter	Rating	Unit	
<b>Common Ratings (<math>T_c=25^\circ\text{C}</math> Unless Otherwise Noted)</b>				
$V_{GS}$	Gate-Source Voltage	±20	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	60	V	
$T_J$	Maximum Junction Temperature	150	°C	
$T_{STG}$	Storage Temperature Range	-55 to 150	°C	
$I_{DM}$	Drain Current-Continuous@ Current-Pulsed	$T_c = 25^\circ\text{C}$ 800	A	
<b>Mounted on Large Heat Sink</b>				
$I_D$	Drain Current-Continuous	$T_c = 25^\circ\text{C}$	240	A
		$T_c = 100^\circ\text{C}$	130	A
$P_D$	Maximum Power Dissipation	150	W	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	0.85	°C/W	
<b>Drain-Source Avalanche Ratings</b>				
EAS	Avalanche Energy, Single Pulsed (Note 1)	520	mJ	

**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ T<sub>J</sub>=25°C (unless otherwise stated)</b>						
V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	--	--	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.6	2.0	V
R <sub>DS(on)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =50A	--	1.1	1.3	mΩ
R <sub>DS(on)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =45A	--	1.4	1.7	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f=1MHz	--	7200	--	pF
C <sub>oss</sub>	Output Capacitance		--	1470	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	30	--	pF
R <sub>g</sub>	Gate Resistance	f=1MHz	--	1.5	--	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =30V, I <sub>D</sub> =50A, V <sub>GS</sub> =4.5V	--	49	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	23	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	15	--	nC
<b>Switching Characteristics (Note 2)</b>						
T <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =30V, I <sub>D</sub> =50A, R <sub>G</sub> =2.5Ω, V <sub>GS</sub> =4.5V	--	38	--	ns
T <sub>r</sub>	Turn-on Rise Time		--	34	--	ns
T <sub>d(off)</sub>	Turn-Off Delay Time		--	52	--	ns
T <sub>f</sub>	Turn-Off Fall Time		--	26	--	ns
<b>Source- Drain Diode Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
I <sub>S</sub>	Diode Forward Current		--	--	240	A
V <sub>SD</sub>	Forward on voltage	I <sub>S</sub> =50A, V <sub>GS</sub> =0V	--	--	1.4	V
T <sub>rr</sub>	Reverse Recovery Time	T <sub>J</sub> =25°C, I <sub>S</sub> =50A, V <sub>R</sub> =50V di/dt=100A/μs	--	68	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	122	--	nC

**Notes:**

1. EAS condition : T<sub>J</sub>=25°C, V<sub>DD</sub>=50V, V<sub>G</sub>=10V, L=0.5mH, R<sub>G</sub>=25Ω
2. Guaranteed by design, not subject to production
3. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T<sub>J</sub>(MAX)=150°C. The SOA curve provides a single pulse rating.

Typical Electrical and Thermal Characteristics

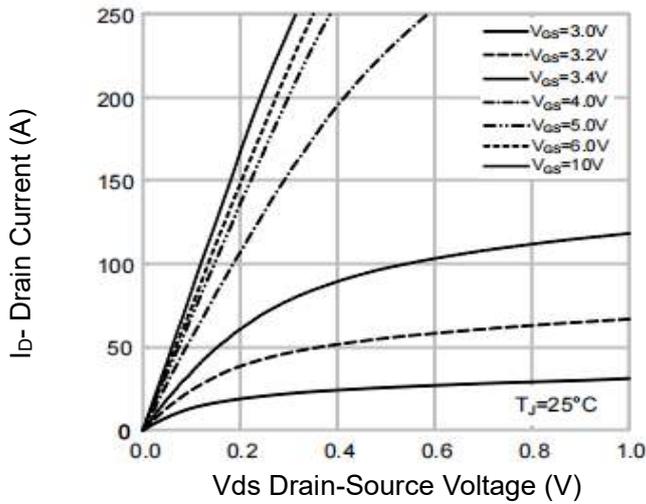


Figure 1 Output Characteristics

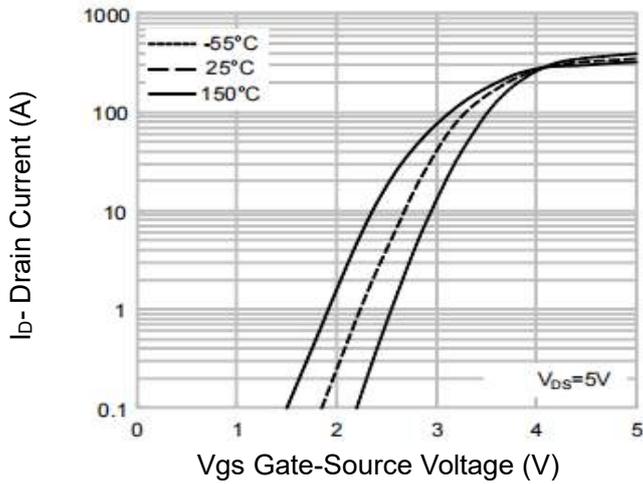


Figure 2 Transfer Characteristics

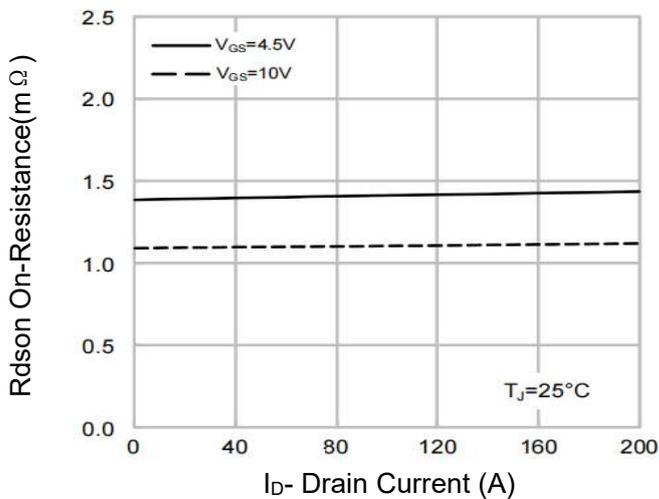


Figure 3 Rdson- Drain Current

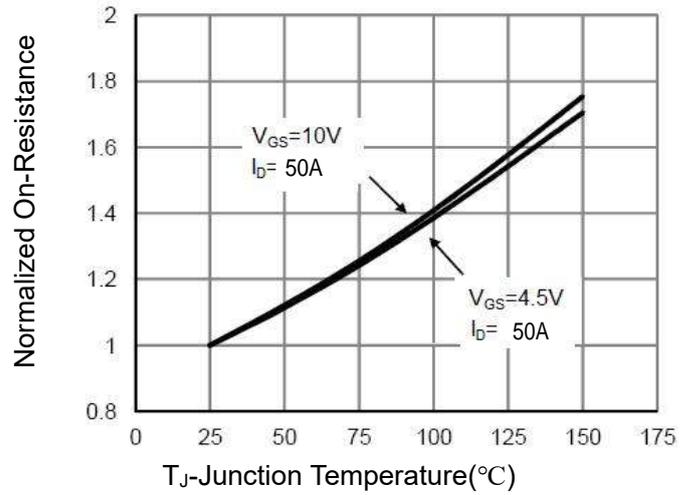


Figure 4 Rdson-Junction Temperature

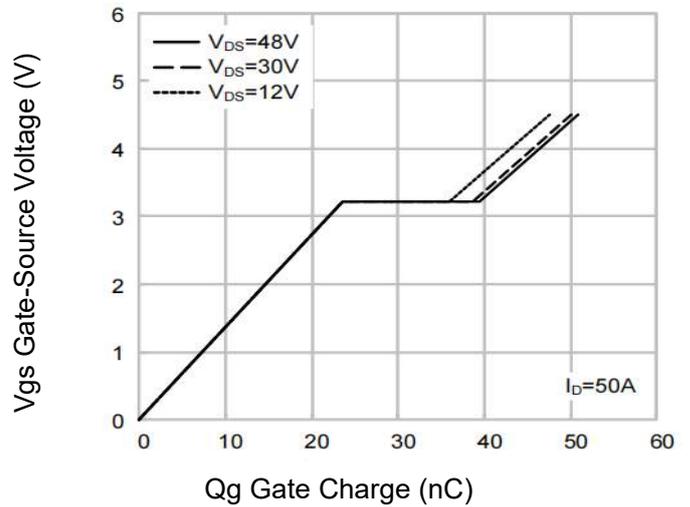


Figure 5 Gate Charge

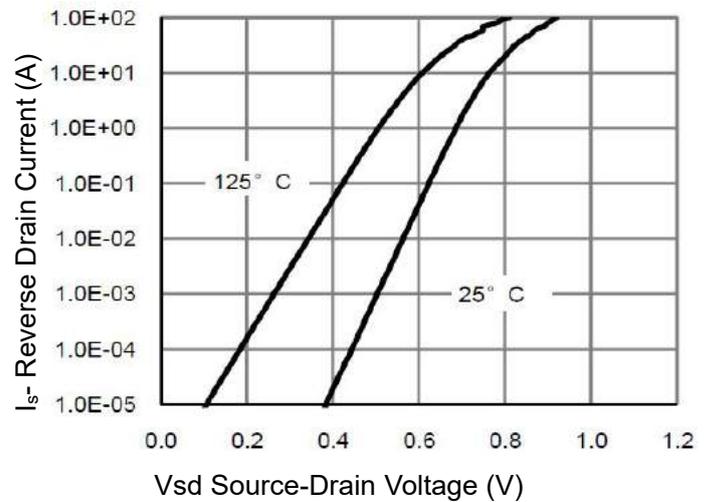


Figure 6 Source- Drain Diode Forward

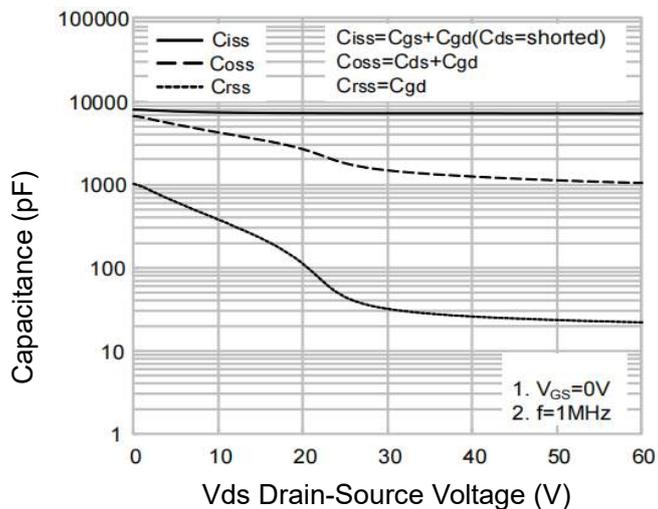


Figure 7 Capacitance vs Vds

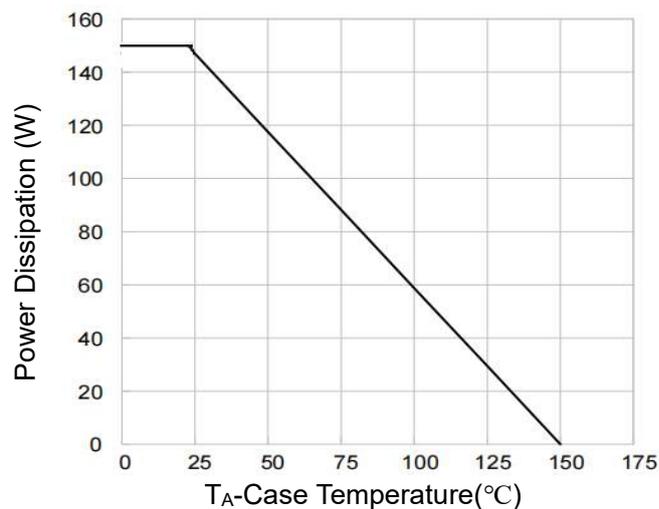


Figure 9 Power De-rating

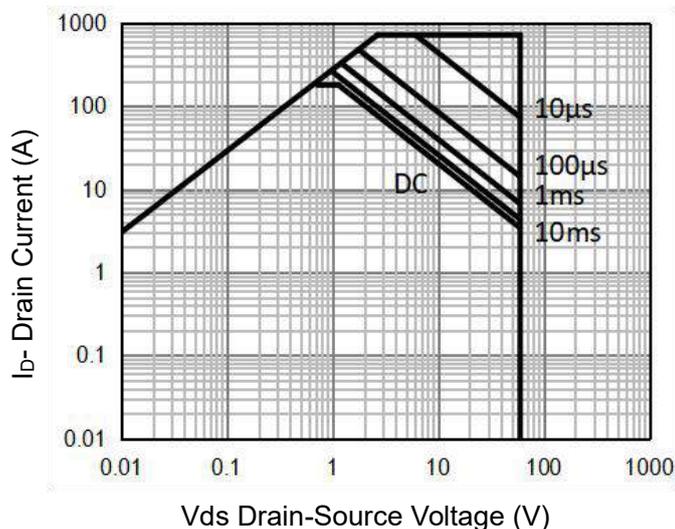


Figure 8 Safe Operation Area (Note 3)

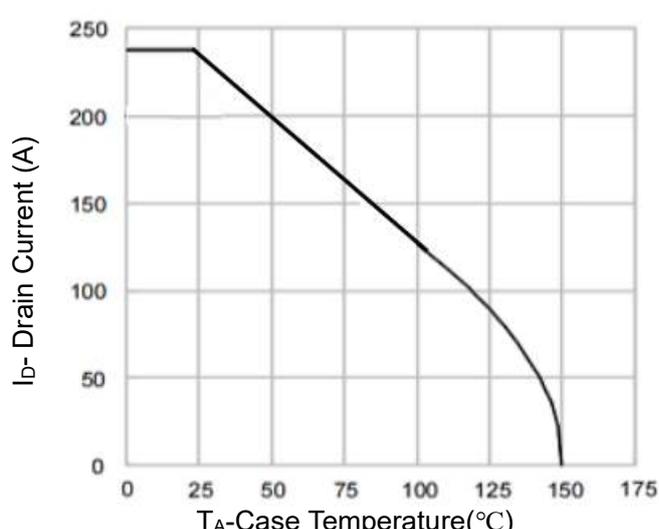


Figure 10 Current De-rating

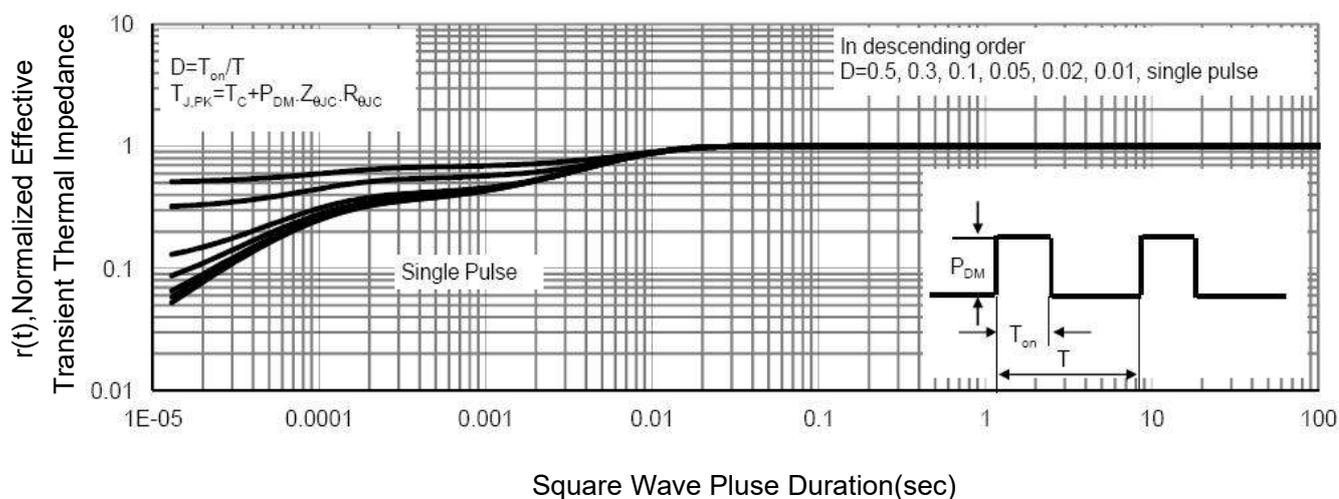
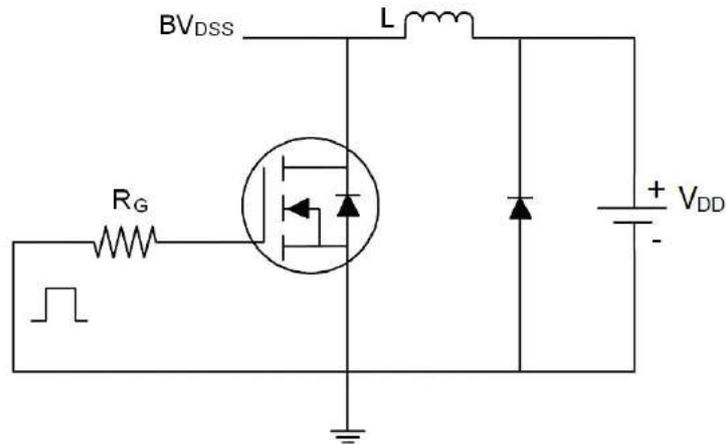


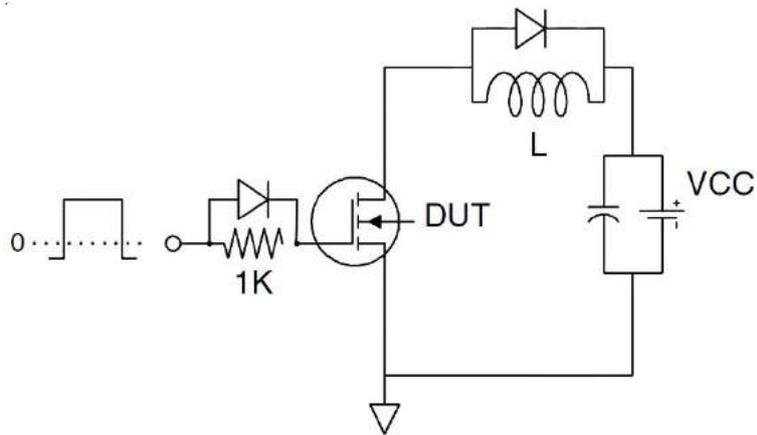
Figure 11 Normalized Maximum Transient Thermal Impedance

### Test Circuit

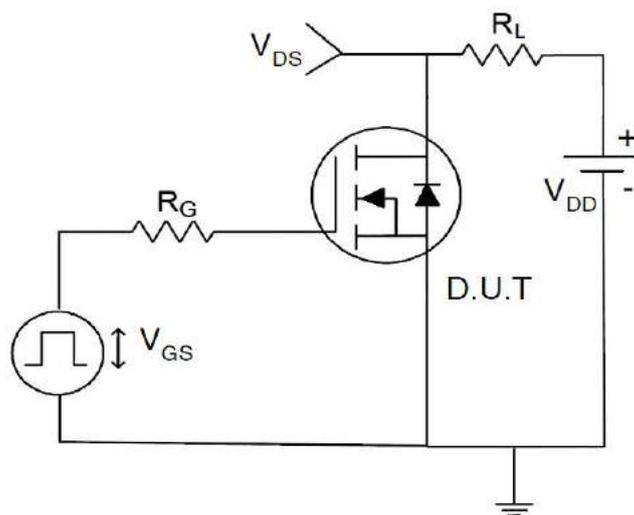
#### 1) $E_{AS}$ test Circuit



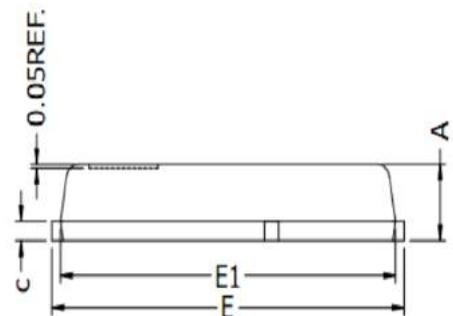
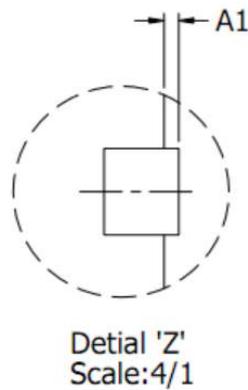
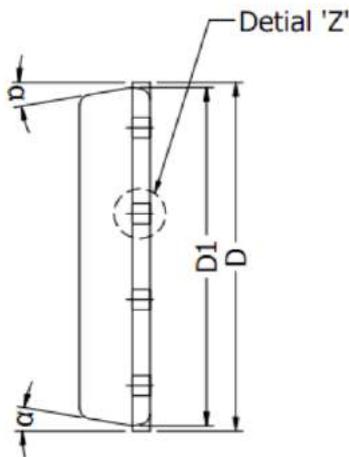
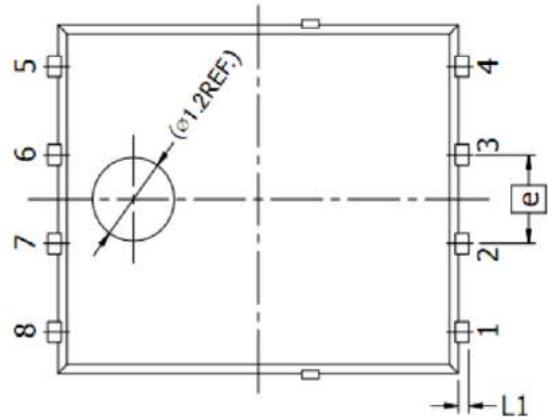
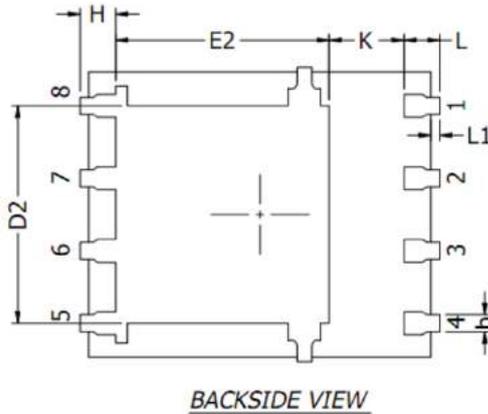
#### 2) Gate charge test Circuit



#### 3) Switch Time Test Circuit



## DFN5x6-8L Package Information



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.30	0.40	0.50
c	0.20	0.25	0.30
D	5.15 BSC		
D1	5.00 BSC		
D2	3.76	3.81	3.86
E	6.15 BSC		
E1	5.80	5.85	5.90
E2	3.45	3.65	3.85
e	1.27 BSC		
H	0.51	0.61	0.71
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.08	0.15	0.23
$\alpha$	10°	11°	12°

## Customer Service

Sales and Service:  
[zj@ztasemi.com](mailto:zj@ztasemi.com)